

Orthodyne Model 20 semiautomatic ultrasonic large wire bonder

- Automatic looping and stepback
- Bonds 4 to 20 mil wire (3 and 25 mil optional)
- Ribbon bonding option
- Uniform, high yield bonding
- Spotlight targeting available
- Deep access, multiple stitch and manual Z options

Outstanding versatility

Orthodyne's Model 20 bonds more kinds of power devices than any other semiautomatic bonder. The standard Model 20 bonds 4 to 20 mil wire to TO-220, TO-218, TO-202, TO-3P and SOT 93 power transistor leadframes, and most power hybrids and discrete power transistors, too. And with Orthodyne's selection of optional equipment, the Model 20 can do much more.

With a simple clamp and bond tool change, the Model 20 bonds deep packages with ribbon or wire. Other bonding tools and options will let you bond wire sizes from 3 to 25 mil. And for even more bonding versatility, Orthodyne also offers manual Z and multiple stitch options. So no matter what kind of package you're bonding—wire or ribbon, hybrid or transistor, flat or deep access—the Orthodyne Model 20 can do the job.

Semiautomatic operation

The Model 20's automatic, adjustable looping and stepback produce uniform loop heights for more consistent, higher quality bonds. For faster bonding, unnecessary stops in the automatic bonding sequence (home, first search, loop and second search) can be electronically locked out. Of course, the Model 20 can also be operated in manual mode.

